



STD5N20L

N-CHANNEL 200V - 0.65Ω - 5A DPAK

STripFET™ MOSFET

Table 1: General Features

| TYPE | V _{DSS} | R _{DS(on)} | I _D | P _w |
|----------|------------------|---------------------|----------------|----------------|
| STD5N20L | 200 V | < 0.7 Ω | 5 A | 33 W |

- TYPICAL R_{DS(on)} = 0.65 Ω @ 5V
- CONDUCTION LOSSES REDUCED
- LOW INPUT CAPACITANCE
- LOW THRESHOLD DEVICE

DESCRIPTION

The STD5N20L utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This is suitable for the most demanding DC Motor Control and lighting application.

APPLICATIONS

- UPS AND MOTOR CONTROL
- LIGHTING

Figure 1: Package

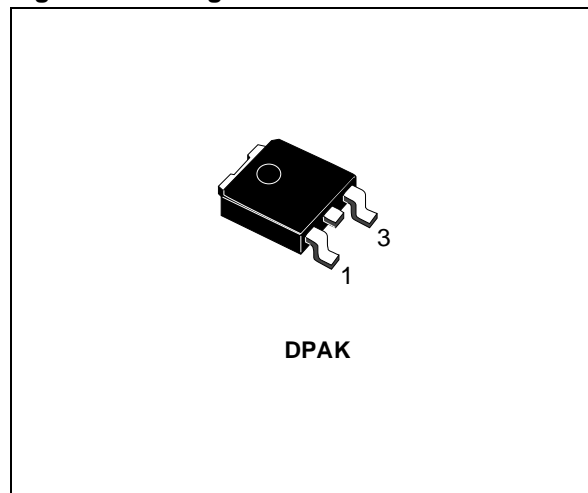


Figure 2: Internal Schematic Diagram

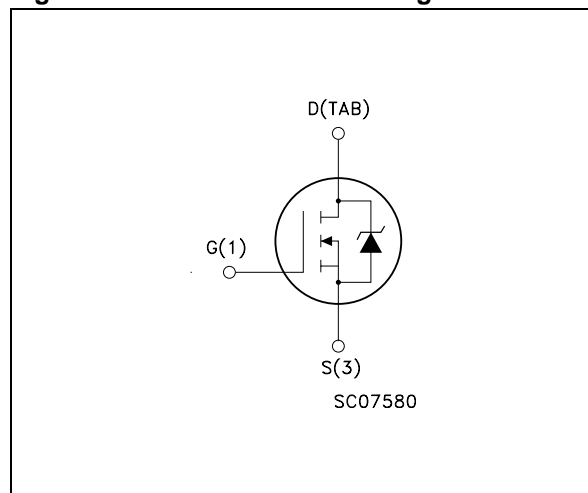


Table 2: Order Codes

| SALES TYPE | MARKING | PACKAGE | PACKAGING |
|------------|---------|---------|-------------|
| STD5N20LT4 | D5N20L | DPAK | TAPE & REEL |

Table 3: Absolute Maximum ratings

| Symbol | Parameter | Value | Unit |
|-------------------|---|------------|---------------------|
| V_{DS} | Drain-source Voltage ($V_{GS} = 0$) | 200 | V |
| V_{DGR} | Drain-gate Voltage ($R_{GS} = 20\text{ k}\Omega$) | 200 | V |
| V_{GS} | Gate- source Voltage | ± 20 | V |
| I_D | Drain Current (continuous) at $T_C = 25^\circ\text{C}$ | 5 | A |
| I_D | Drain Current (continuous) at $T_C = 100^\circ\text{C}$ | 3.6 | A |
| $I_{DM}(\bullet)$ | Drain Current (pulsed) | 20 | A |
| P_{TOT} | Total Dissipation at $T_C = 25^\circ\text{C}$ | 33 | W |
| | Derating Factor | 0.27 | W/ $^\circ\text{C}$ |
| T_{stg} | Storage Temperature | -55 to 150 | $^\circ\text{C}$ |
| T_j | Operating Junction Temperature | | |

(\bullet) Pulse width limited by safe operating area

Table 4: Thermal Data

| | | | |
|----------------|--|------|---------------------------|
| $R_{thj-case}$ | Thermal Resistance Junction-case Max | 3.75 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-amb}$ | Thermal Resistance Junction-ambient Max | 100 | $^\circ\text{C}/\text{W}$ |
| T_l | Maximum Lead Temperature For Soldering Purpose | 275 | $^\circ\text{C}$ |

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)

Table 5: On/Off

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|--|---|------|------|-----------|--------------------------------|
| $V_{(BR)DSS}$ | Drain-source Breakdown Voltage | $I_D = 250\ \mu\text{A}, V_{GS} = 0$ | 200 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current ($V_{GS} = 0$) | $V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}, T_C = 125^\circ\text{C}$ | | | 1 10 | μA μA |
| I_{GSS} | Gate-body Leakage Current ($V_{DS} = 0$) | $V_{GS} = \pm 20\text{V}$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 50\ \mu\text{A}$ | 1 | | 2.5 | V |
| $R_{DS(on)}$ | Static Drain-source On Resistance | $V_{GS} = 5\ \text{V}, I_D = 2.5\ \text{A}$ | | 0.65 | 0.7 | Ω |

Table 6: Dynamic

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|----------------------------|------|----------------------|
| g_{fs} (2) | Forward Transconductance | $V_{DS} = 15\text{ V}$, $I_D = 5\text{ A}$ | | 6.5 | | S |
| C_{iss} C_{oss} C_{rss} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$ | | 242 44 6 | | pF pF pF |
| $t_{d(on)}$ t_r $t_{d(off)}$ t_f | Turn-on Delay Time Rise Time Turn-off Delay Time Fall Time | $V_{DD} = 100\text{ V}$, $I_D = 2.5\text{ A}$ $R_G = 4.7\Omega$, $V_{GS} = 5\text{ V}$ (Resistive Load see Figure 14) | | 11.5 21.5 14 15.5 | | ns ns ns ns |
| Q_g Q_{gs} Q_{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 160\text{ V}$, $I_D = 5\text{ A}$, $V_{GS} = 5\text{ V}$ | | 5 1.5 3 | 6 | nC nC nC |

Table 7: Source Drain Diode

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|--|------|------------------|------|---------------|
| I_{SD} | Source-drain Current | | | | 5 | A |
| I_{SDM} (*) | Source-drain Current (pulsed) | | | | 20 | A |
| V_{SD} (1) | Forward On Voltage | $I_{SD} = 5\text{ A}$, $V_{GS} = 0$ | | | 1.5 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 100\text{ V}$, $T_j = 25^\circ\text{C}$ (see test circuit, see Figure 15) | | 93 237 5.1 | | ns nC A |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 5\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 100\text{ V}$, $T_j = 150^\circ\text{C}$ (see test circuit, see Figure 15) | | 97 286 5.9 | | ns nC A |

(1) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(2) Starting $T_j = 25^\circ\text{C}$, $I_d = 5\text{ A}$, $V_{DD} = 50\text{ V}$

(*) Pulse width limited by safe operating area

Figure 3: Safe Operating Area

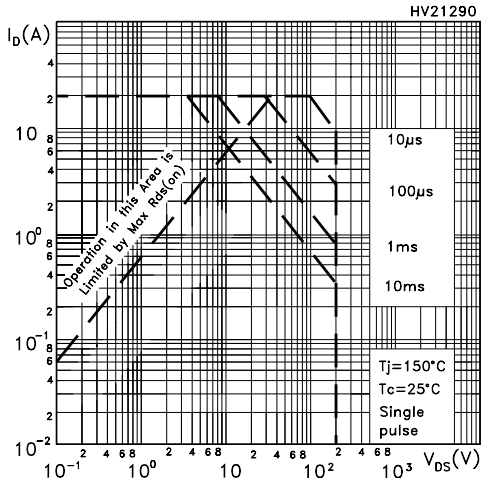


Figure 4: Output Characteristics

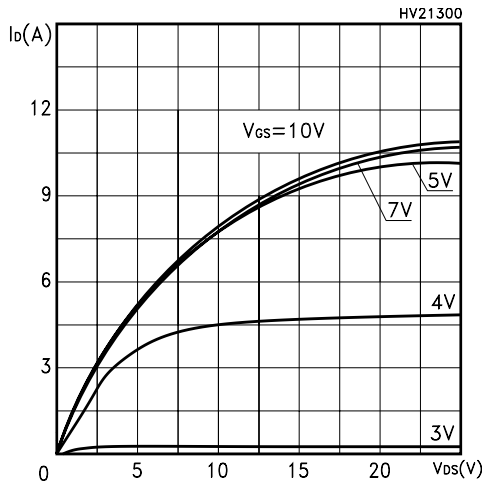


Figure 5: Transconductance

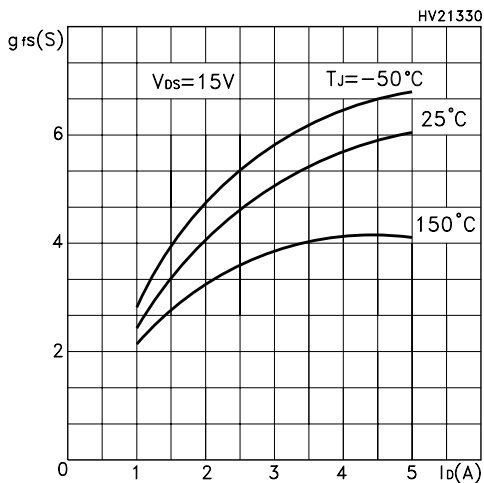


Figure 6: Thermal Impedance

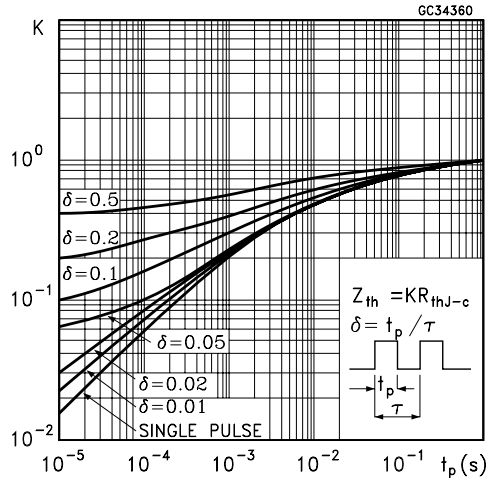


Figure 7: Transfer Characteristics

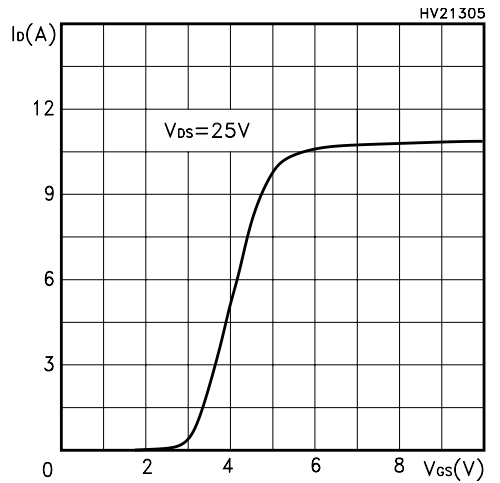


Figure 8: Static Drain-source On Resistance

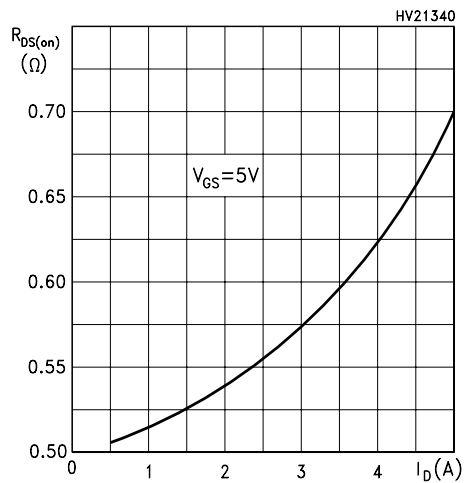


Figure 9: Gate Charge vs Gate-source Voltage

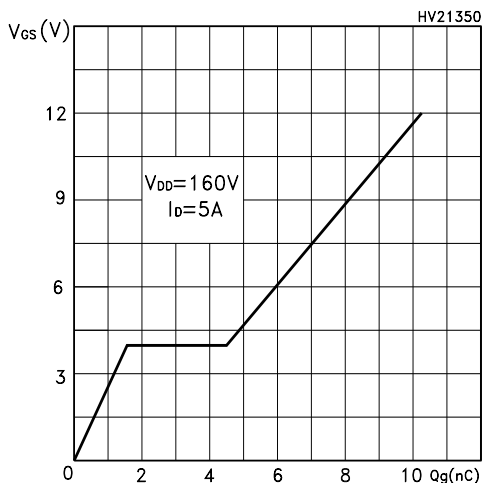


Figure 10: Normalized Gate Threshold Voltage vs Temperature

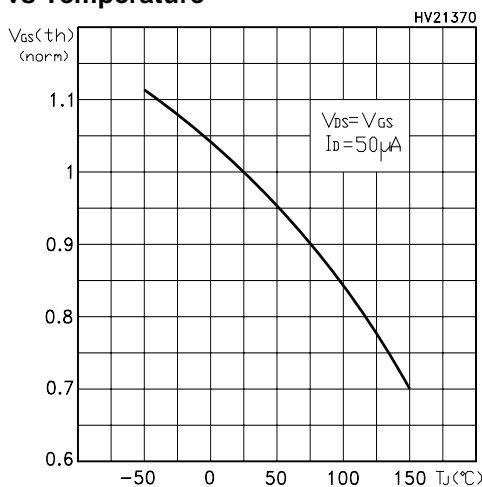


Figure 11: Source-Drain Diode Forward Characteristics

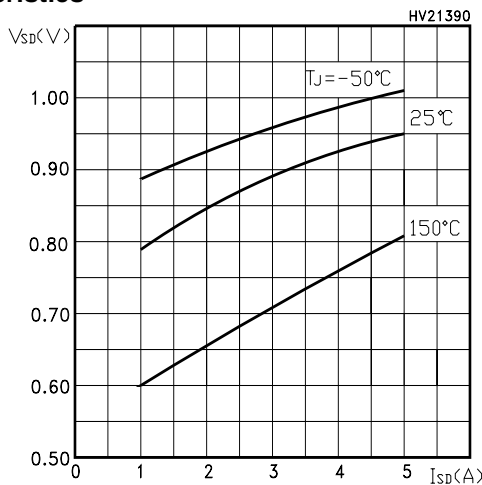


Figure 12: Capacitance Variations

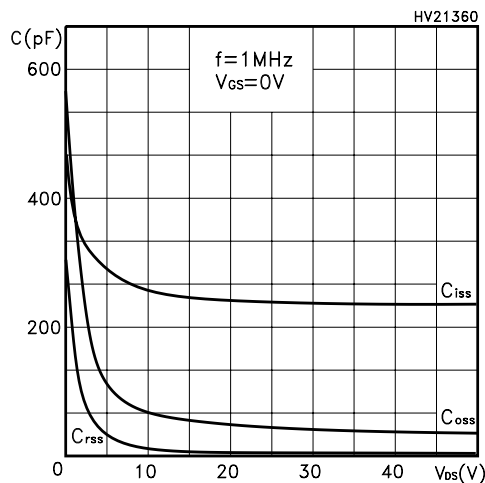


Figure 13: Normalized On Resistance vs Temperature

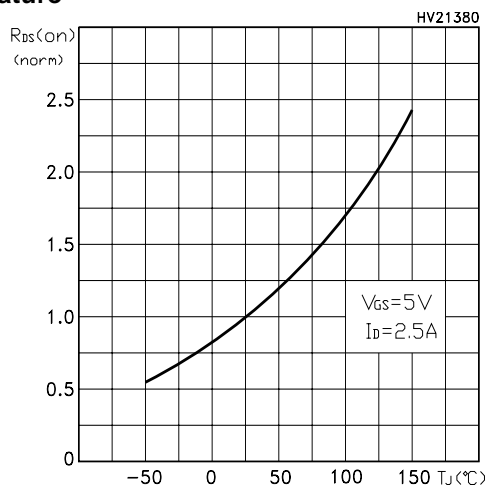


Figure 14: Switching Times Test Circuit For Resistive Load

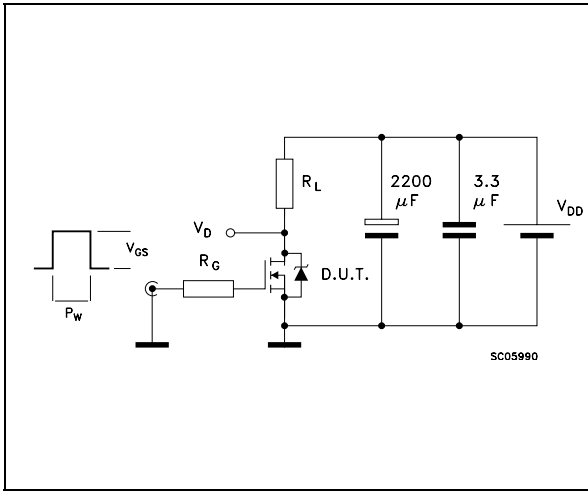


Figure 15: Test Circuit For Inductive Load Switching and Diode Recovery Times

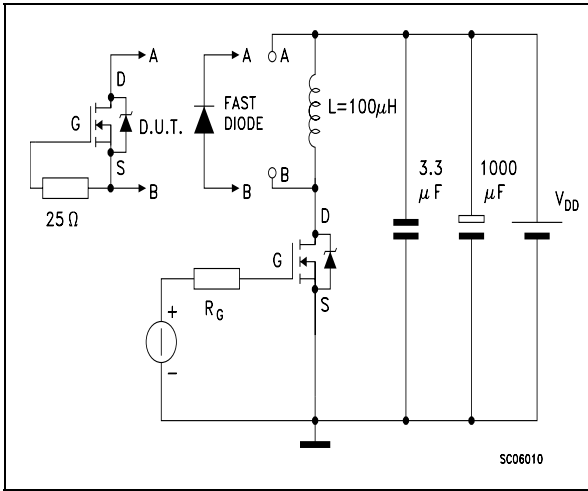
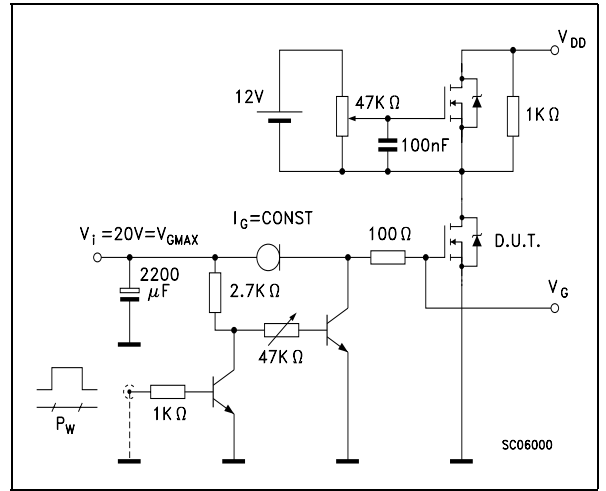
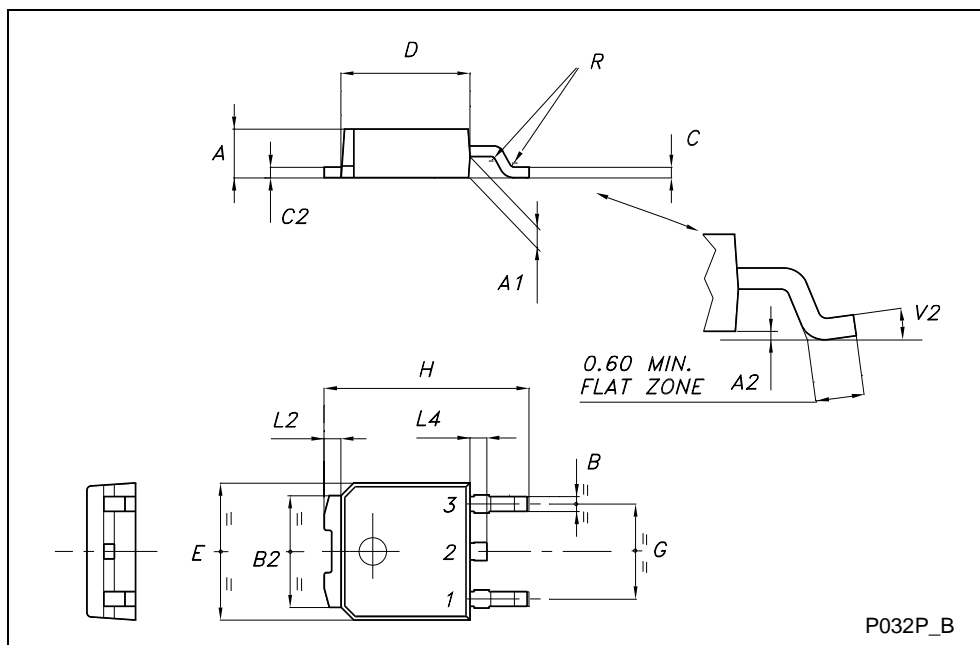


Figure 16: Gate Charge Test Circuit

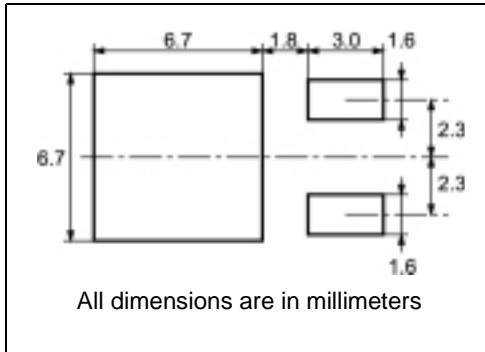


TO-252 (DPAK) MECHANICAL DATA

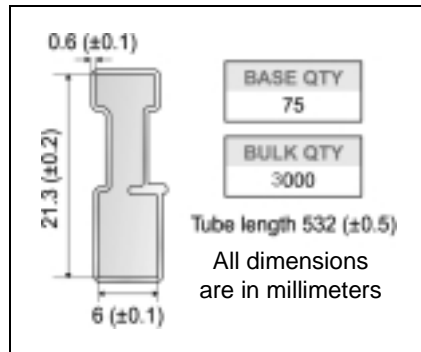
| DIM. | mm | | | inch | | |
|------|------|------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.20 | | 2.40 | 0.087 | | 0.094 |
| A1 | 0.90 | | 1.10 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.90 | 0.025 | | 0.035 |
| B2 | 5.20 | | 5.40 | 0.204 | | 0.213 |
| C | 0.45 | | 0.60 | 0.018 | | 0.024 |
| C2 | 0.48 | | 0.60 | 0.019 | | 0.024 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.60 | 0.252 | | 0.260 |
| G | 4.40 | | 4.60 | 0.173 | | 0.181 |
| H | 9.35 | | 10.10 | 0.368 | | 0.398 |
| L2 | | 0.8 | | | 0.031 | |
| L4 | 0.60 | | 1.00 | 0.024 | | 0.039 |
| V2 | 0° | | 8° | 0° | | 0° |



DPAK FOOTPRINT



TUBE SHIPMENT (no suffix)*



TAPE AND REEL SHIPMENT (suffix "T4")*

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start 2.5mm min. width

G measured at hub

REEL MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 16.4 | 18.4 | 0.645 | 0.724 |
| N | 50 | | 1.968 | |
| T | | 22.4 | | 0.881 |

| BASE QTY | BULK QTY |
|----------|----------|
| 2500 | 2500 |

TAPE MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 6.8 | 7 | 0.267 | 0.275 |
| B0 | 10.4 | 10.6 | 0.409 | 0.417 |
| B1 | | 12.1 | | 0.476 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.5 | | 0.059 | |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 7.4 | 7.6 | 0.291 | 0.299 |
| K0 | 2.55 | 2.75 | 0.100 | 0.108 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 7.9 | 8.1 | 0.311 | 0.319 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 40 | | 1.574 | |
| W | 15.7 | 16.3 | 0.618 | 0.641 |

For machines not only including shaft and rails concerning around the

TOP COVER TAPE

10 pitches cumulative tolerance on tape + / - 0.2 mm

Center line of cavity

User Direction of Feed

FEED DIRECTION

Bending radius R min.

* on sales type

Table 8: Revision History

| Date | Revision | Description of Changes |
|--------------|-----------------|---|
| 08-June-2004 | 2 | New Stylesheet. Datasheet according to PCN DSG-TRA/04/532 |
| 20-Sep-2004 | 3 | Changes on Table 3, and on Figure 3. |

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